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MAR 08 2005

FAX Transmittal

Date: MARCH 2, 2005

Pages: 9 (including this one)

TO:	Office of Petitions
FAX:	(703) 872-9306
FROM:	Steve Gratton
FAX:	(303) 989 6538

**Re: Serial no. 09/266,237
Docket No. 97-1433**

See attached "Supplement To Petition To Accept Late Payment Of Issue Fee".

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

WARREN M. FARNWORTH
~~SALMAN AKRAM~~

Serial No. 09/266,237

Art Unit: 2829

Filing Date: 03/10/1999

Examiner: KOBERT, R.

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MAR 08 2005

For: TEST INTERCONNECT AND TEST SYSTEM
FOR BUMPED SEMICONDUCTOR COMPONENTS
(AS AMENDED)

Attorney Docket No. 97-1433

**SUPPLEMENT TO
PETITION TO ACCEPT LATE PAYMENT OF ISSUE FEE**

MARCH 2, 2005

Mail Stop Petition
Commissioner For Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant has filed a Petition To Accept Late Payment Of Issue Fee dated October 11, 2004. However, the Petition was defective in that it did not include proof that the Notice of Allowance And Fees Due mailed on 06/08/2004 was not received by the Attorney for Applicant. This Supplement is being filed with proof that the Notice of Allowance And Fees Due was a non received communication.

With respect to proof, MPEP 711.03(c)I.A, requires a statement from the Practitioner that the communication was not received, along with a copy of the docket records for the period for response indicating where the communication

would have been entered had it been received. In view of the foregoing requirements, Attorney for Applicant hereby provides the following statements and documents.

1. Attorney For Applicant did not receive the original "Notice Of Allowance And Fees Due" mailed on 06/08/2004 by the Patent Office.

2. Attorney for Applicant has searched the file jacket and the docket records for docket no. 97-1433 (serial no. 09/266,237). Both the file jacket and the docket records indicate that the above communication was not received.

3. Attached to this Supplement are docket records for "The Law Office Of Steve Gratton" for the period from 06/01/2004 to 10/19/2004, which includes the three month period for response (06/08/2004 to 09/08/2004) for the non received communication.

4. These docket records have been labeled as Exhibits A-D. Exhibit A is dated June 1, 2004. Exhibit B is dated July 21, 2004. Exhibit C is dated September 16, 2004. Exhibit D is dated October 19, 2004.

5. The present application docket no. 97-1433 (serial no. 09/266,237) is contained on page 6 of the docket records.

Exhibit A dated June 1, 2004 includes the entry under "ACTION DUE" for docket no. 97-1433 (serial no. 09/266,237) "Filed Amendment 4/26/04".

Exhibit B dated July 21, 2004 includes the entry under "ACTION DUE" for docket no. 97-1433 (serial no. 09/266,237) "Filed Amendment 4/26/04".


Exhibit C dated September 16, 2004 includes the handwritten entry under "ACTION DUE" for docket no. 97-1433 (serial no. 09/266,237) "Filed Issue Fee Transmittal + Petition 10/11/04".

Exhibit D dated October 19, 2004 includes the entry under "ACTION DUE" for docket no. 97-1433 (serial no. 09/266,237) "Filed Issue Fee Transmittal and Petition" 10/11/04.

6. These docket records indicate that the Notice of Allowance And Fees Due mailed on 06/08/2004 for docket no. 97-1433 (serial no. 09/266,237) was not received by Attorney for Applicant in the time period for response of (06/08/2004 to 09/08/2004).

In view of the foregoing Applicant requests that the holding of abandonment be withdrawn. In addition, Applicant requests that the "Part B-Fee(s) Transmittal", the "Fee Address Indication Form" and the issue fee be accepted and processed.

Respectfully submitted:


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CERTIFICATE OF TRANSMISSION UNDER 37 C.F.R. §1.8

I hereby certify that this correspondence entitled "Supplement To Accept Late Payment Of Issue Fee" (pages 1-4 and Exhibits A-D) is being facsimile transmitted to the United States Patent and Trademark Office on 03/02/2005 to Fax no. (571) 273-0025 for the Office of Petitions.

March 2, 2005

Date of Signature



Stephen A. Gratton
Attorney for Applicant #28,418

EXHIBIT A

KGD DOCKET

CASE NO.	TITLE (SHORT)	FILING DATE	COMMENTS	ACTION DUE
97-1433 09/266,237	Test Interconnect For Bumped Components (Apparatus)	3/10/99	Warren, Salman	Filed Amendment 4/26/04.
97-1433.1 09/844,532	Test Interconnect For Bumped Components (Method of Fab)	4/27/01	Warren, Salman Div of 97-1433	Filed Amendment & IDS 4/30/04.
97-1433.2 10/832,483	Test Interconnect For Bumped Components	4/26/04	Warren, Salman Div of 97-1433	Awaiting OA.
99-311.1 09/834,805	Test Interconnect For Bumped Components (Method of Fab)	4/12/01	Warren, Salman Div of 99-0311	Paid Issue Fee by 3/22/04.
99-311.2	Test Interconnect for Bumped	7/18/02	Div of 99-0311	Paid Issue Fee 2/13/04
99-311.3 10/666,292	Contact for Semiconductor Components	9/18/03	Cont of 99-0311.2	Awaiting OA. <i>STATUS: LATER 7/15/04</i>
99-0285.2 10/329,212	Interconnect With Variable Flexure (Method for Test)	12/24/02	Cont of 99-0285.1	Awaiting OA. <i>Respond to OA by 7/15/04</i>
99-0323.2 10/334,407	Method for Fabricating Package	12/31/02	Cont of 99-0323.1	Respond to OA by 2/18/04.*
99-068.2 09/653,366	Polymer Support Member for BGA (Method)	9/1/00	Warren, Alan Cont of 99-068.1	Filed Issue Fee 3/31/04.
99-068.3 10/693,380	Polymer Support Member for BGA (Method)	10/24/03	Warren, Alan Cont of 99-0068.2	Updated IDS 2/6/04.
99-0703.1 10/187,915	Silicon Carbide Interconnect (Method)	7/1/02	Div of 99-0703	Respond to OA by 8/10/04.*
99-0703.3 10/660,367	Silicon Carbide Contact	9/11/03		Awaiting OA.
99-0812.2 10/659,828	Semiconductor Component Having Test Contacts	9/12/03	Cont. of 99-0812.1	Awaiting OA. Respond to OA by 9/17/04 Updated IDS 11/11/03.

*Response due

THE LAW OFFICE
OF STEVE GRATTON

June 1, 2004

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EXHIBIT C

*Added + new
documented + Patent
9/11/04*

INDEX DOCKET

CASE NO.	TITLE (SHORT)	FILING DATE	COMMENTS	ACTION DUE
97-1433 09/266,237	Test Interconnect For Bumped Components (Apparatus)	3/10/99	Warren, Salman	Filed Amendment 4/26/04 <i>Amended Patent of Salman 9/26/04</i>
97-1433.1 09/844,532	Test Interconnect For Bumped Components (Method of Fab)	4/27/01	Warren, Salman Div of 97-1433	Filed Respond 7/23/04.
97-1433.2 10/832,483	Test Interconnect For Bumped Components	4/26/04	Warren, Salman Div of 97-1433	Awaiting OA.
99-311.1 09/834,805	Test Interconnect For Bumped Components (Method of Fab)	4/12/01	Warren, Salman Div of 99-0311	Paid Issue Fee by 3/22/04.
99-311.2	Test Interconnect for Bumped	7/18/02	Div of 99-0311	Paid Issue Fee 2/13/04. Status Letter filed 7/21/04.
99-311.3 10/666,292	Contact for Semiconductor Components	9/18/03	Cont of 99-0311.2	Awaiting OA.
99-0285.2 10/329,212	Interconnect With Variable Flexure (Method for Test)	12/24/02	Cont of 99-0285.1	Filed Amendment 6/22/04.
99-0323.2 10/334,407	Method for Fabricating Package	12/31/02	Cont of 99-0323.1	Paid Issue Fee 8/23/04.
99-068.3 10/693,380	Polymer Support Member for BGA (Method)	10/24/03	Warren, Alan Cont of 99-0068.2	Updated IDS 2/6/04.
99-0703.1 10/187,915	Silicon Carbide Interconnect (Method)	7/1/02	Div of 99-0703	Filed Amendment & IDS 8/27/04.
99-0703.3 10/660,367	Silicon Carbide Contact	9/11/03		Awaiting OA.
99-0812.2 10/689,828	Semiconductor Component Having Test Contacts	9/12/03	Cont. of 99-0812.1	Filed Amendment & IDS 9/17/04.

*Response due

THE LAW OFFICE
OF STEVE GRATTON

September 16, 2004

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EXHIBIT B

KGD DOCKET

CASE NO.	TITLE (SHORT)	FILING DATE	COMMENTS	ACTION DUE
97-1433 09/266,237	Test Interconnect For Bumped Components (Apparatus)	3/10/99	Warren, Salman	Filed Amendment 4/26/04.
97-1433.1 09/844,532	Test Interconnect For Bumped Components (Method of Fab)	4/27/01	Warren, Salman Div of 97-1433	Filed Amendment & IDS 4/30/04. <i>filed Respond 7/23/04</i>
97-1433.2 10/832,483	Test Interconnect For Bumped Components	4/26/04	Warren, Salman Div of 97-1433	Awaiting OA.
99-311.1 09/834,805	Test Interconnect For Bumped Components (Method of Fab)	4/12/01	Warren, Salman Div of 99-0311	Paid Issue Fee by 3/22/04.
99-311.2	Test Interconnect for Bumped	7/18/02	Div of 99-0311	Paid Issue Fee 2/13/04. Status Letter filed 7/21/04.
99-311.3 10/666,292	Contact for Semiconductor Components	9/18/03	Cont of 99-0311.2	Awaiting OA.
99-0285.2 10/329,212	Interconnect With Variable Flexure (Method for Test)	12/24/02	Cont of 99-0285.1	Filed Amendment 6/22/04.
99-0323.2 10/334,407	Method for Fabricating Package	12/31/02	Cont of 99-0323.1	Filed RFR 1/15/04. <i>PAID Issue fee 8/23/04</i>
99-068.3 10/693,380	Polymer Support Member for BGA (Method)	10/24/03	Warren, Alan Cont of 99-0068.2	Updated IDS 2/6/04.
99-0703.1 10/187,915	Silicon Carbide Interconnect (Method)	7/1/02	Div of 99-0703	Respond to OA by 8/10/04. <i>filed Amendment + IDS 8/27/04</i>
99-0703.3 10/660,367	Silicon Carbide Contact	9/11/03		Awaiting OA.
99-0612.2 10/659,828	Semiconductor Component Having Test Contacts	9/12/03	Cont. of 99-0812.1	Respond to OA by 9/17/04.*

*Response due

THE LAW OFFICE
OF STEVE GRATTON

July 21, 2004

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EXHIBIT D

KGD DOCKET

CASE NO.	TITLE (SHORT)	FILING DATE	COMMENTS	ACTION DUE
97-1433 09/266,237	Test Interconnect For Bumped Components (Apparatus)	3/10/99	Warren, Salman	Filed Issue Fee Transmittal and Petition 10/11/04.
97-1433.1 09/844,532	Test Interconnect For Bumped Components (Method of Fab)	4/27/01	Warren, Salman Div of 97-1433	Filed Response 7/23/04.
97-1433.2 10/832,483	Test Interconnect For Bumped Components	4/26/04	Warren, Salman Div of 97-1433	Awaiting OA.
99-311.1 09/834,805	Test Interconnect For Bumped Components (Method of Fab)	4/12/01	Warren, Salman Div of 99-0311	Paid Issue Fee 3/22/04.
99-311.2	Test Interconnect for Bumped	7/18/02	Div of 99-0311	Paid Issue Fee 2/13/04. Status Letter filed 7/21/04.
99-311.3 10/666,292	Contact for Semiconductor Components	9/18/03	Cont of 99-0311.2	Awaiting OA.
99-0285.2 10/329,212	Interconnect With Variable Flexure (Method for Test)	12/24/02	Cont of 99-0285.1	Filed Amendment 6/22/04.
99-0323.2 10/334,407	Method for Fabricating Package	12/31/02	Cont of 99-0323.1	Paid Issue Fee 8/23/04.
99-068.3 10/693,380	Polymer Support Member for BGA (Method)	10/24/03	Warren, Alan Cont of 99-0068.2	Updated IDS 2/6/04.
99-0703.1 10/187,915	Silicon Carbide Interconnect (Method)	7/1/02	Div of 99-0703	Filed Amendment & IDS 8/27/04. <i>Respond to Fed by 2/10/05</i>
99-0703.3 10/660,367	Silicon Carbide Contact	9/11/03		Awaiting OA.
99-0812.2 10/659,828	Semiconductor Component Having Test Contacts	9/12/03	Cont. of 99-0812.1	Filed Amendment & IDS 9/17/04.

*Response due

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October 19, 2004

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